Super SIDELED®
High-Current LED

LG A672, LP A672

Abgekündigt nach PD_078_02 - werden durch LG A676 und LP A676 ersetzt werden
Obsolete acc. to PD_078_02 - will be replaced by LG A676 and LP A676

Besondere Merkmale

- **Gehäusetyp:** weißes SMT Gehäuse
- **Besonderheit des Bauteils:** Abstrahlung parallel zur Platine, deshalb ideal zur Einkopplung in Lichtleiter; höherer zulässiger Betriebsstrom
- **Wellenlänge:** 570 nm (grün), 560 nm (pure green)
- **Abstrahlwinkel:** Lambertscher Strahler (120°)
- **Technologie:** GaAsP (grün), GaP (pure green)
- **optischer Wirkungsgrad:** 1,5 lm/W (grün), 0,6 lm/W (pure green)
- **Gruppierungsparameter:** Lichtstärke
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten und Wellenlöten (TTW)
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 12 mm Gurt mit 2000/Rolle, ø330 mm

Features

- **package:** white SMT package
- **feature of the device:** radiation direction parallel to PCB, so an ideal LED for coupling in light guides; higher permissible current
- **wavelength:** 570 nm (green), 560 nm (pure green)
- **viewing angle:** Lambertian Emitter (120°)
- **technology:** GaAsP (green), GaP (pure green)
- **optical efficiency:** 1.5 lm/W (green), 0.6 lm/W (pure green)
- **grouping parameter:** luminous intensity
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering and TTW soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 12 mm tape with 2000/reel, ø330 mm

Anwendungen

- Hinterleuchtung (LCD, Schalter, Tasten, Displays)
- Einkopplung in Lichtleiter
- Innenbeleuchtung im Automobilbereich (z.B. Instrumentenbeleuchtung, u.ä.)

Applications

- backlighting (LCD, switches, keys, displays)
- coupling into light guide
- interior automotive lighting. (e.g. dashboard backlighting, etc.)

Typ Type	Emissions-farbe Color of Emission	Farbe der Lichtaustritts-fläche Color of the Light Emitting Area	Lichtstärke Luminous Intensity I_F = 50 mA I_V (mcd)	Lichtstrom Luminous Flux I_F = 50 mA Φ_V (mlm)	Bestellnummer Ordering Code
■ LG A672-P1Q1-1	green	colorless clear	45.0 ... 90.0	190 (typ.)	Q62703Q5000
■ LG A672-Q1R2-1			71.0 ... 180.0	350 (typ.)	Q62703Q5001
■ LP A672-L2M2-1	pure green	colorless clear	14.0 ... 28.0	62 (typ.)	Q62703Q5056
■ LP A672-M2P1-1			22.4 ... 56.0	110 (typ.)	Q62703Q5057

■ Abgekündigt nach PD_078_02 - werden durch LG_LP A676 ersetzt werden
Obsolete acc. to PD_078_02 - will be replaced by LG_LP A676
Letzte Bestellung / Last Order: 30.09.2003
Letzte Lieferung / Last Delivery: 31.03.2004

*Anm.: -1 gesamter Farbbereich (siehe **Seite 4**)*

Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.

*Note: -1 Total color tolerance range (siehe **page 4**)*

The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.
No packing unit / tape ever contains more than one luminous intensity half group.

Grenzwerte
Maximum Ratings

Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Betriebstemperatur Operating temperature range	T_{op}	– 40 … + 100	°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 … + 100	°C
Sperrschichttemperatur Junction temperature	T_j	+ 100	°C
Durchlassstrom Forward current	I_F	50	mA
Stoßstrom Surge current $t \leq 10$ µs, $D = 0.005$	I_{FM}	1	A
Sperrspannung[1)] Reverse voltage	V_R	12	V
Leistungsaufnahme Power consumption	P_{tot}	160	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient Sperrschicht/Lötpad Junction/solder point Montage auf PC-Board FR 4 (Padgröße ≥ 16 mm²) mounted on PC board FR 4 (pad size ≥ 16 mm²)	 $R_{th\ JA}$ $R_{th\ JS}$	 330 100	 K/W K/W

[1)] für kurzzeitigen Betrieb geeignet / suitable for short term application

Kennwerte (T_A = 25 °C)
Characteristics

Bezeichnung **Parameter**		**Symbol** **Symbol**	**Werte** **Values**		**Einheit** **Unit**
			LG	**LP**	
Wellenlänge des emittierten Lichtes Wavelength at peak emission I_F = 50 mA	(typ.)	λ_{peak}	572	557	nm
Dominantwellenlänge [1] Dominant wavelength I_F = 50 mA	(typ.)	λ_{dom}	570 ± 6	560 ± 6	nm
Spektrale Bandbreite bei 50 % $I_{rel\ max}$ Spectral bandwidth at 50 % $I_{rel\ max}$ I_F = 50 mA	(typ.)	$\Delta\lambda$	25	22	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) Viewing angle at 50 % I_V	(typ.) (typ.)	2φ	120	120	Grad deg.
Durchlassspannung [2] Forward voltage I_F = 50 mA	(typ.) (max.)	V_F V_F	2.6 3.5	2.6 2.7	V V
Sperrstrom Reverse current V_R = 12 V	(typ.) (max.)	I_R I_R	0.01 10	0.01 10	µA µA
Temperaturkoeffizient von λ_{peak} Temperature coefficient of λ_{peak} I_F = 50 mA; –10°C ≤ T ≤ 100°C	(typ.)	$TC_{\lambda peak}$	0.11	0.11	nm/K
Temperaturkoeffizient von λ_{dom} Temperature coefficient of λ_{dom} I_F = 50 mA; –10°C ≤ T ≤ 100°C	(typ.)	$TC_{\lambda dom}$	0.07	0.05	nm/K
Temperaturkoeffizient von V_F Temperature coefficient of V_F I_F = 50 mA; –10°C ≤ T ≤ 100°C	(typ.)	TC_V	– 2.0	– 2.0	mV/K
Optischer Wirkungsgrad Optical efficiency I_F = 50 mA	(typ.)	η_{opt}	1.5	0.6	lm/W

[1] Wellenlängen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ±1 nm ermittelt.
Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of ±1 nm.

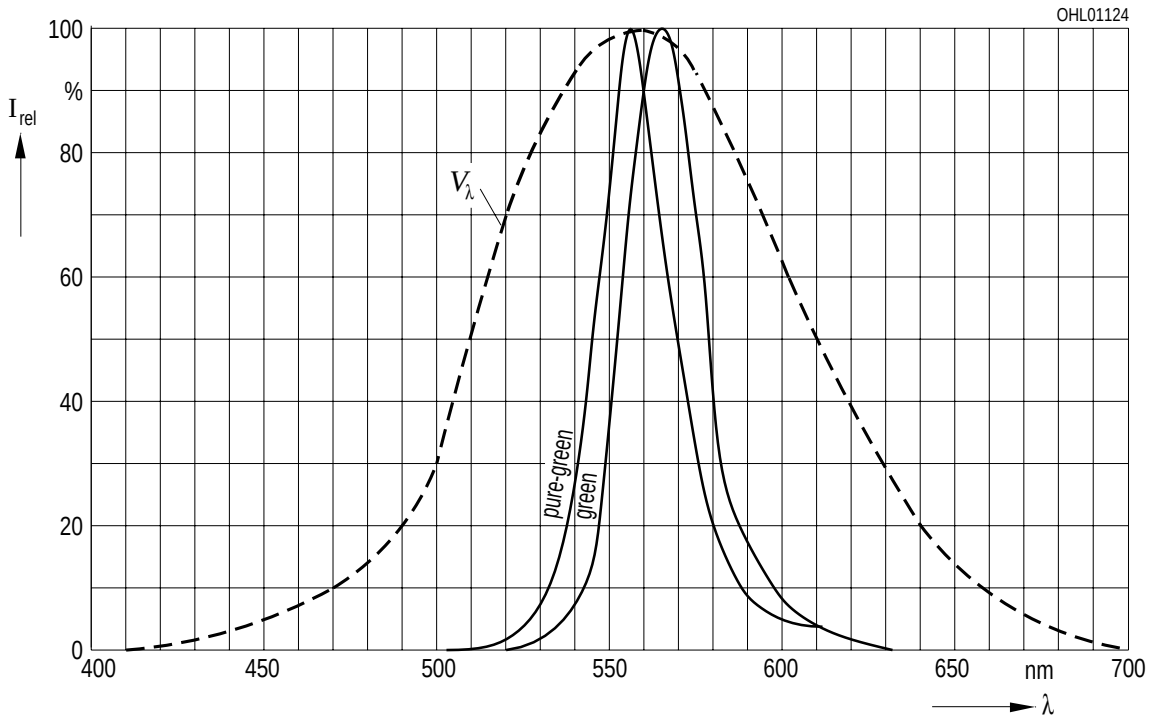
[2] Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von ±0,1 V ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of ±0.1 V.

Helligkeits-Gruppierungsschema
Luminous Intensity Groups

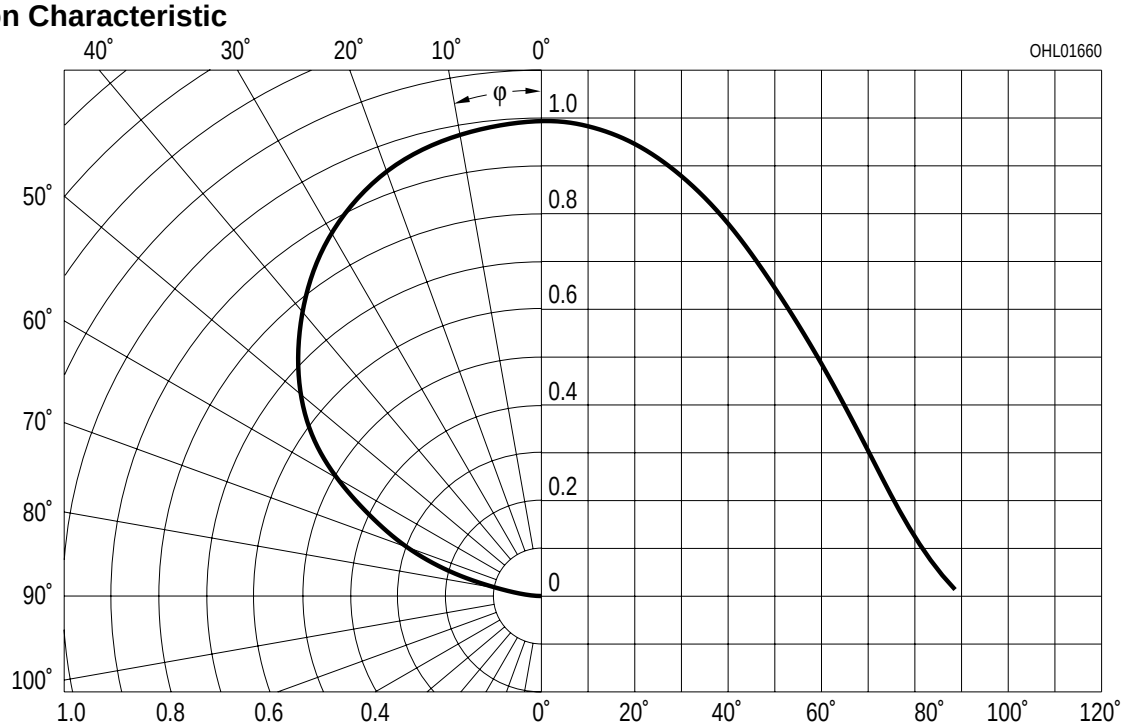
Lichtgruppe **Luminous Intensity Group**	**Lichtstärke** **Luminous Intensity** **I_V (mcd)**	**Lichtstrom** **Luminous Flux** **Φ_V (mlm)**
L2	14.0 … 18.0	50 (typ.)
M1	18.0 … 22.4	60 (typ.)
M2	22.4 … 28.0	75 (typ.)
N1	28.0 … 35.5	95 (typ.)
N2	35.5 … 45.0	120 (typ.)
P1	45.0 … 56.0	150 (typ.)
P2	56.0 … 71.0	190 (typ.)
Q1	71.0 … 90.0	240 (typ.)
Q2	90.0 …112.0	300 (typ.)
R1	112.0 …140.0	380 (typ.)
R2	140.0 …180.0	480 (typ.

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ± 11% ermittelt.
Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of ± 11%.

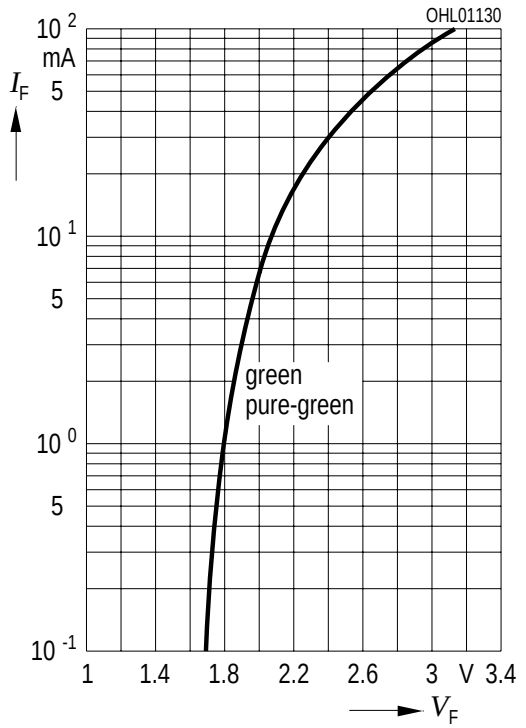
Relative spektrale Emission $I_{rel} = f(\lambda)$, T_A = 25 °C, I_F = 50 mA
Relative Spectral Emission
V(λ) = spektrale Augenempfindlichkeit
Standard eye response curve



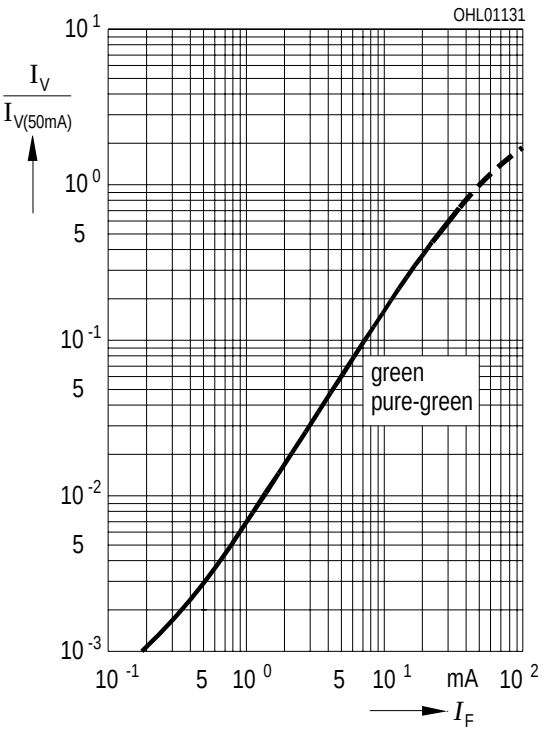
Abstrahlcharakteristik $I_{rel} = f(\varphi)$
Radiation Characteristic



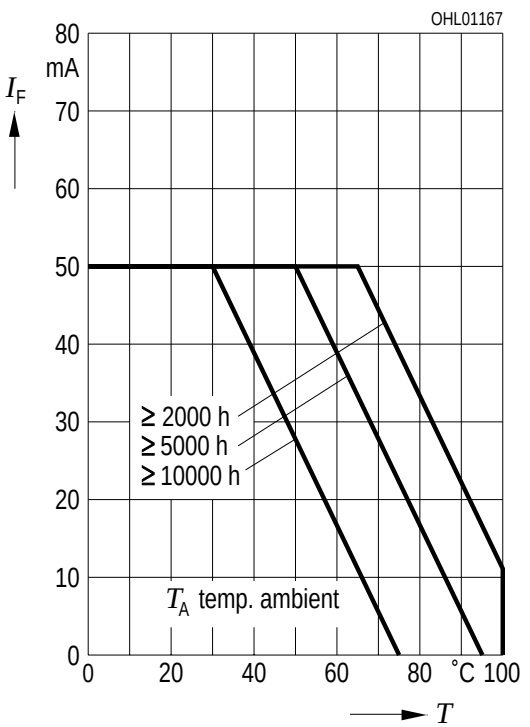
Durchlassstrom $I_F = f(V_F)$
Forward Current
T_A = 25 °C



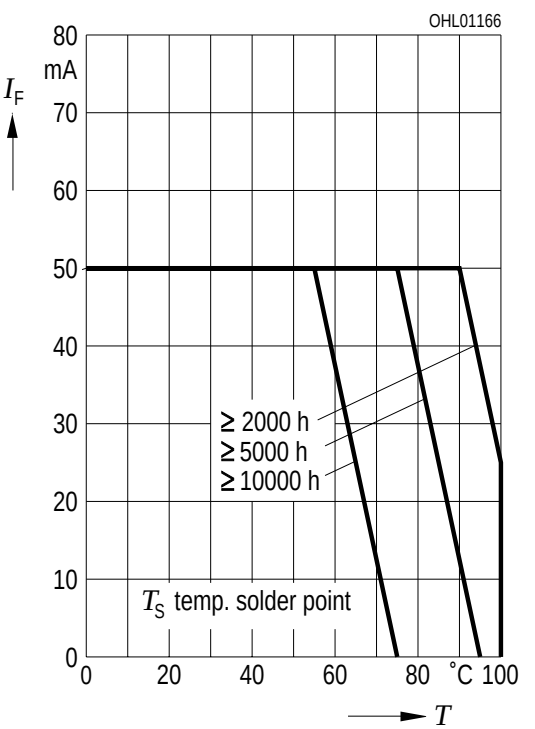
Relative Lichtstärke $I_V/I_{V(50\ mA)} = f(I_F)$
Relative Luminous Intensity
T_A = 25 °C



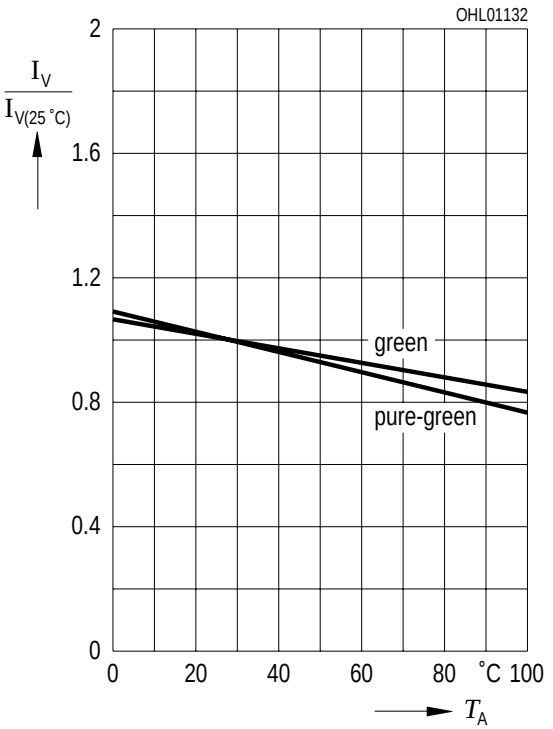
Maximal zulässiger Durchlassstrom $I_F = f(T)$
Max. Permissible Forward Current



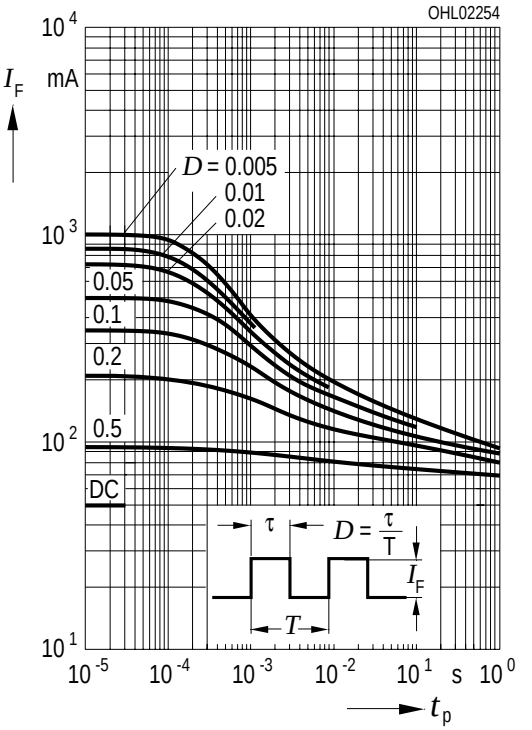
Maximal zulässiger Durchlassstrom $I_F = f(T)$
Max. Permissible Forward Current



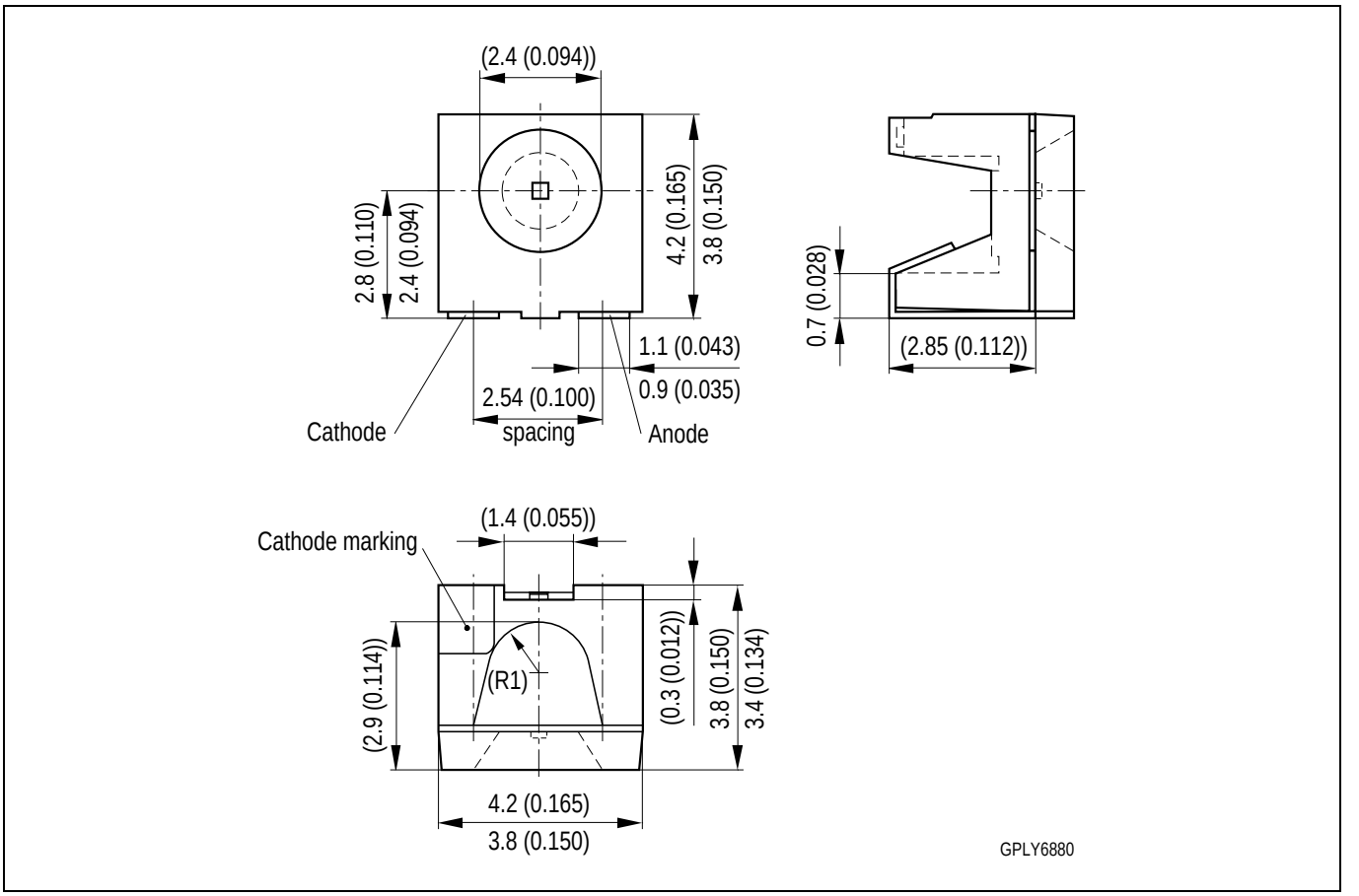
Relative Lichtstärke $I_V/I_{V(25\,°C)} = f(T_A)$
Relative Luminous Intensity
I_F = 50 mA



Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
Duty cycle D = parameter, T_A = 25 °C



Maßzeichnung
Package Outlines

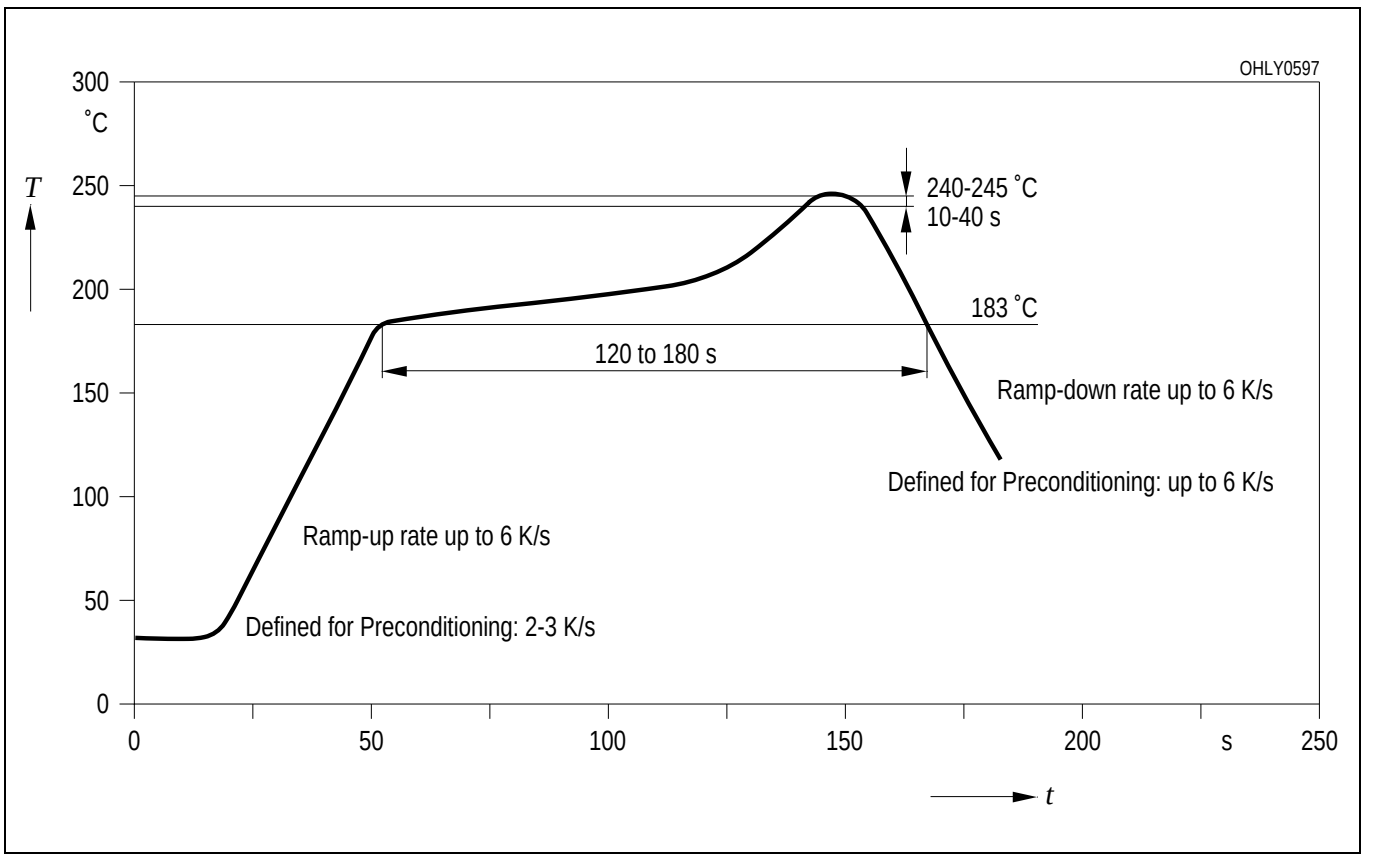


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

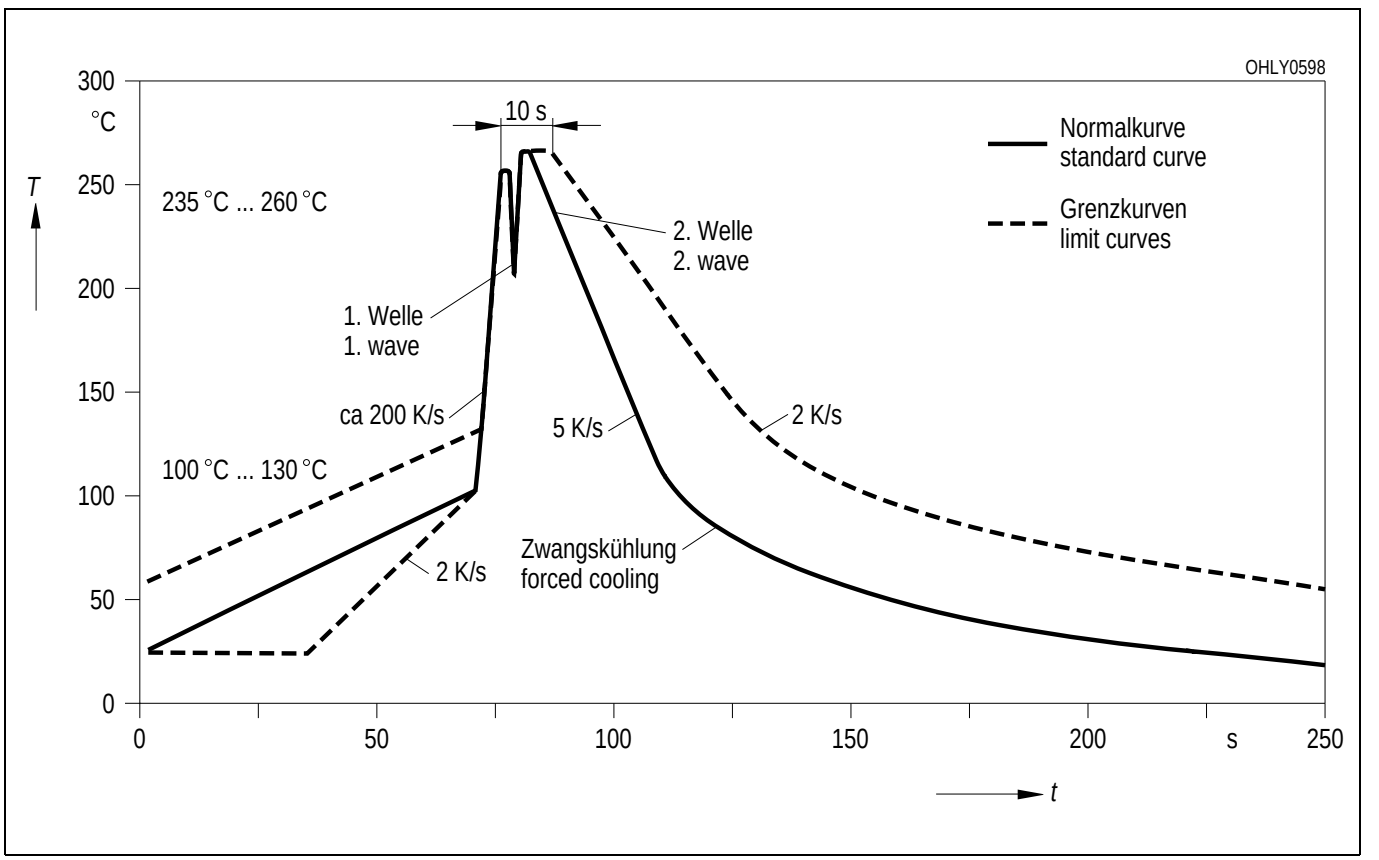
Kathodenkennung: abgeschrägte Ecke
Cathode mark: bevelled edge
Gewicht / Approx. weight: 40 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

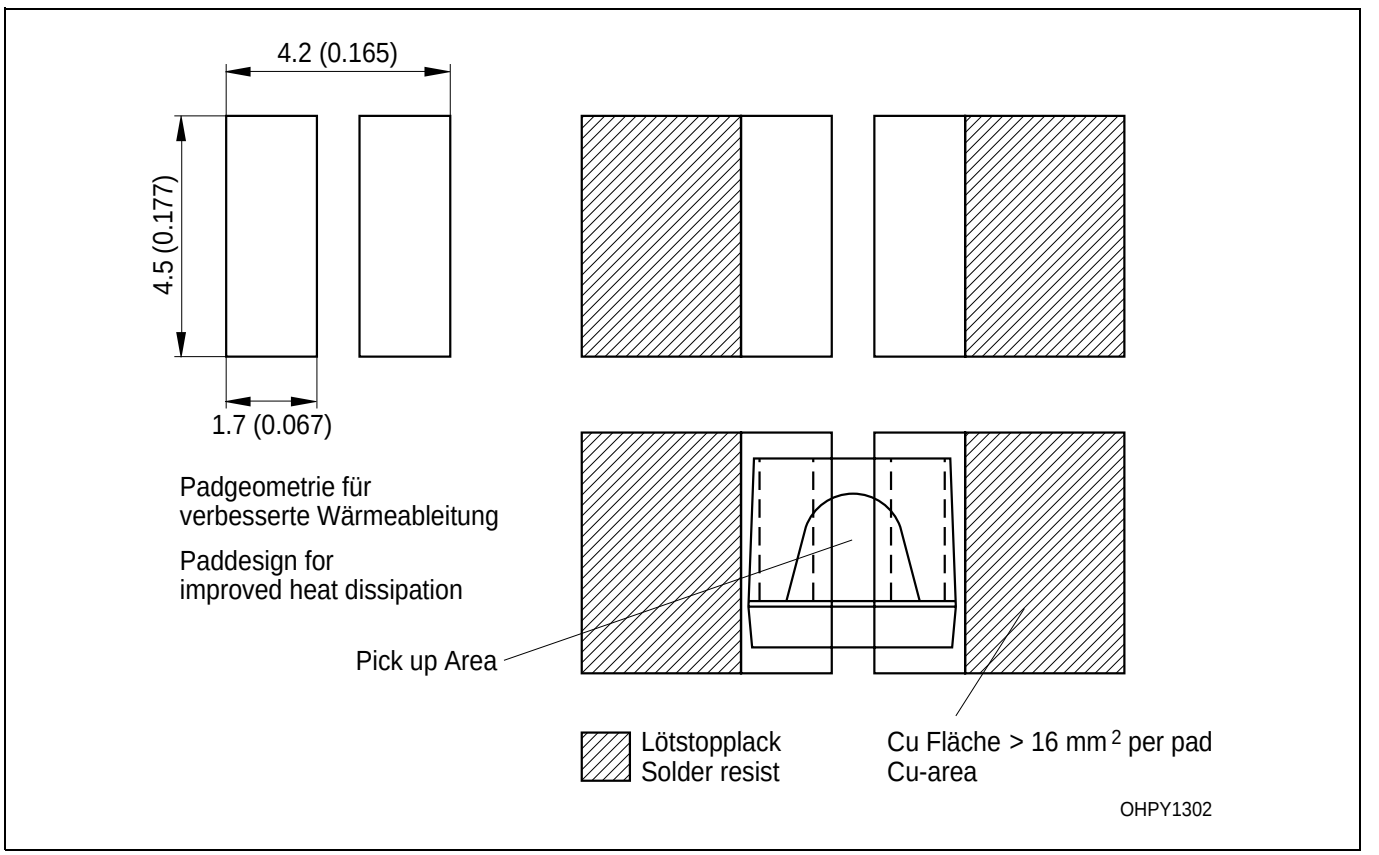
IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)

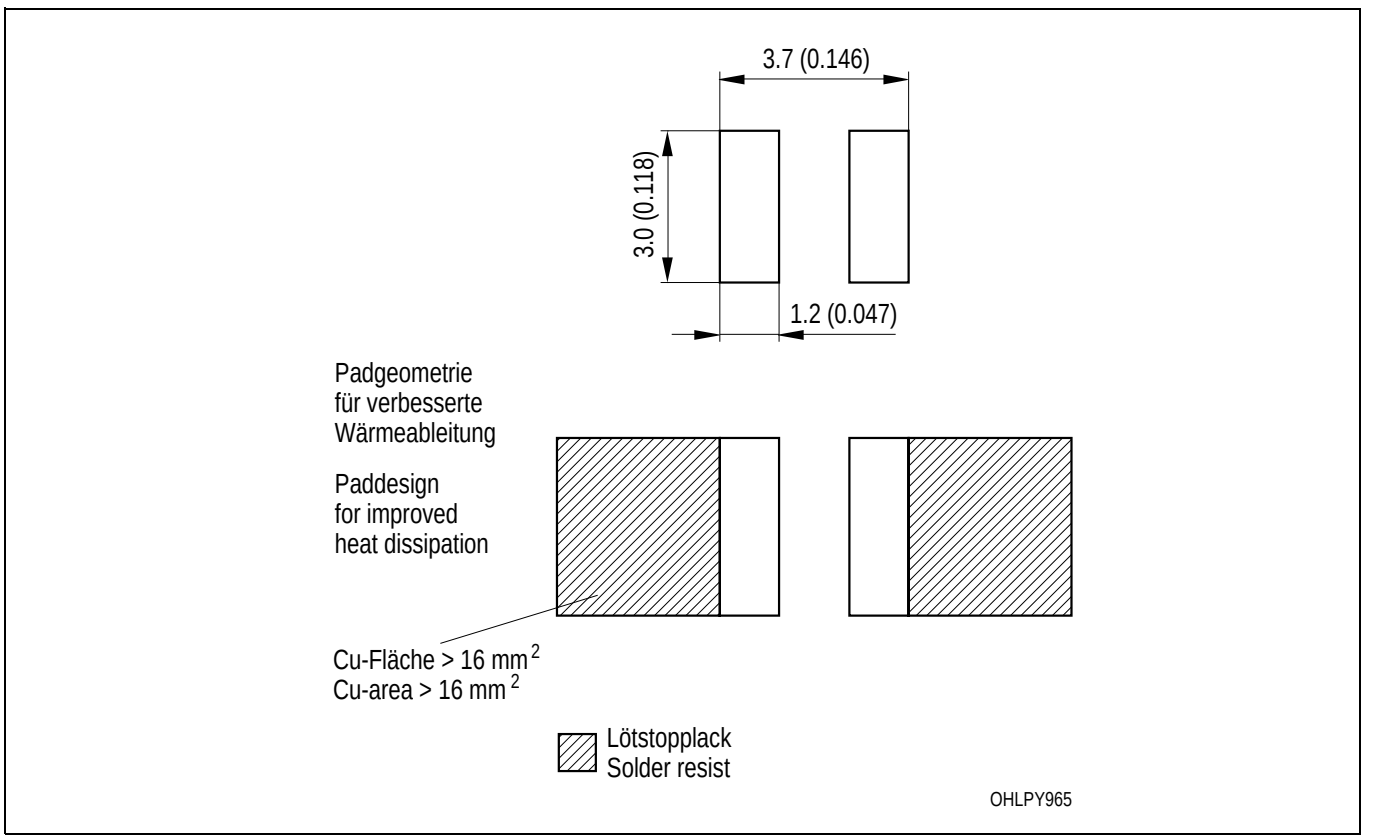


Empfohlenes Lötpaddesign Wellenlöten (TTW)
Recommended Solder Pad TTW Soldering



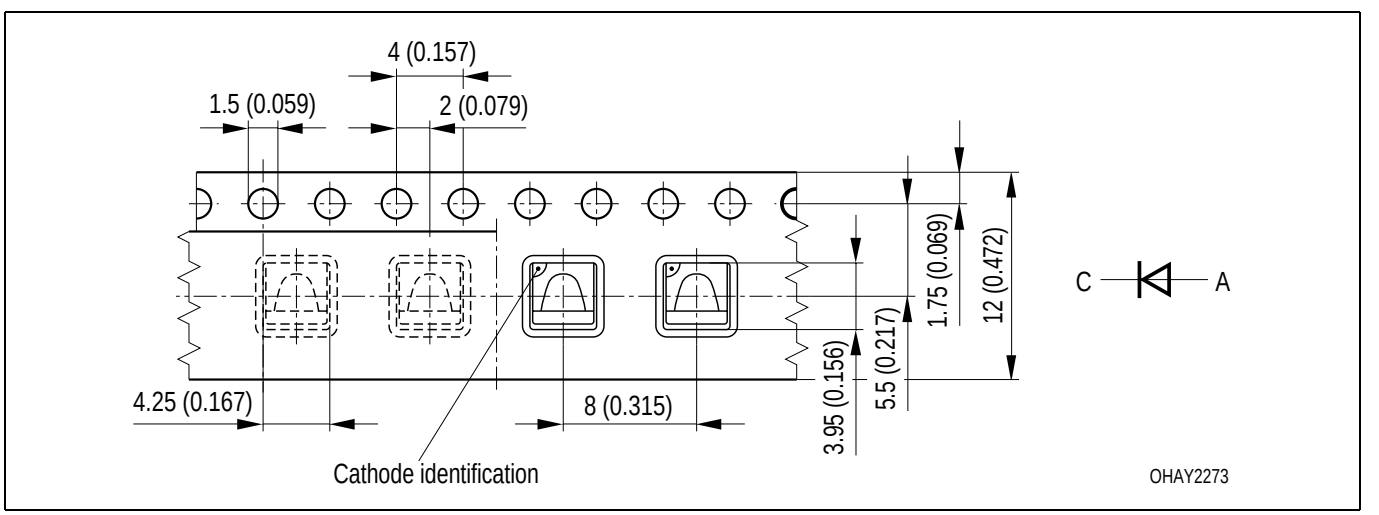
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Empfohlenes Lötpaddesign IR Reflow Löten
Recommended Solder Pad IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Gurtung / Polarität und Lage Verpackungseinheit 2000/Rolle, ø330 mm
Method of Taping / Polarity and Orientation Packing unit 2000/reel, ø330 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2003-08-04		Date of change
Previous Version: 2002-11-18		
Page	**Subjects (major changes since last revision)**	
12	recommended solder pad	
12	recommended solder pad extended to TTW soldering	
13	annotations	2002-07-23
13	recommended solder pad (IR reflow soldering)	2002-08-01
3, 4	value (reverse voltage from 5 V to 12 V)	2002-09-18
all	not for new designs	2002-11-18
1, 2	Obsolete	2003-08-04

Published by OSRAM Opto Semiconductors GmbH
Wernerwerkstrasse 2, D-93049 Regensburg

Attention please!
The information describes the type of component and shall not be considered as assured characteristics.
All typical data and graphs are basing on representative samples, but don't represent the production range. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version in the Internet.
Packing
Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.
Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components [1] may only be used in life-support devices or systems [2] with the express written approval of OSRAM OS.
[1] A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.
[2] Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.